

L Number	Hits	Search Text	DB	Time stamp
-	1313	((438/674) or (438/678) or (438/687)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 12:56
-	418	((((438/674) or (438/678) or (438/687)).CCLS.) and electroless	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 12:57
-	325	(((((438/674) or (438/678) or (438/687)).CCLS.) and electroless) and (copper or Cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 12:58
-	0	(((((438/674) or (438/678) or (438/687)).CCLS.) and electroless) and (copper or Cu)) and (laminar near flow)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 12:58
-	129	(((((438/674) or (438/678) or (438/687)).CCLS.) and electroless) and (copper or Cu)) and flow	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 13:30
-	1	electroless and (copper or Cu) and (laminar near flow)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 13:00
-	4157	electroless near copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 13:00
-	3	(electroless near copper) same (laminar near flow)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 13:00
-	100	(electroless near plating) near apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 13:30
-	1	((electroless near plating) near apparatus) and (laminar near flow)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 13:31
-	15	((electroless near plating) near apparatus) and ((several or plurality) same (wafer or wafers))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 13:35
-	474	((205/775) or (204/193)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 13:35
-	6	((((205/775) or (204/193)).CCLS.) and (electroless near plating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/10/19 13:35